## In the Specification:

Please replace the paragraph beginning on page 6, line 12 with the following amended paragraph:

FIG. 2 is a schematic diagram illustrating the chip architecture for testing integrated circuit chip 100. In FIG. 2, integrated circuit chip 100 includes a multiplicity of macro-circuits 150 and a multiplicity of isolation circuits 155. There is one isolation circuit 155 for each macro-circuit 150. Each macro circuit 150/isolation circuit 155 is coupled to a macro-circuit scan multiplexer and control logic 160 by a corresponding bus 165. Each bus 165 includes wires for at least macro-circuit scan-out signals and isolation circuit scan-in, scan-out and control signals. Macro-circuit scan multiplexer and control logic 160 is further coupled to all the NPG circuit scan chains 170 by a bus 175. Bus 175 includes wires for at least multiple NPG scan-in signals and multiple NPG scan-out signals. Macro-circuit scan multiplexer and control logic 160 is also coupled to multiple I/O pads 180A by bus 185A for receiving scan-in signals from off chip, multiple I/O pads 180B by bus 185B for sending scan-out signals off chip and multiple I/O pads 180C by bus 185C for receiving mode and configuration control signals from a tester. Mode and configuration control signals are used by macro-circuit scan multiplexer and control logic 160 to configure scan chains for testing either macro-circuits 150 or the NPG circuits of integrated circuit chip 100 as illustrated in FIGs. 3A, 3B, 3C and 4 and described *infra*. While not necessarily separate signals, mode control can be thought of as selecting whether to test macro-circuits or NPG circuits and configuration signals can be thought of as selecting groups of macro-circuits to test together. While isolation circuits 155 are illustrated "outside" of macrocircuits 150, the isolation circuits may be incorporated within each macro-circuit.